Silicon P Channel MOS FET High Speed Power Switching

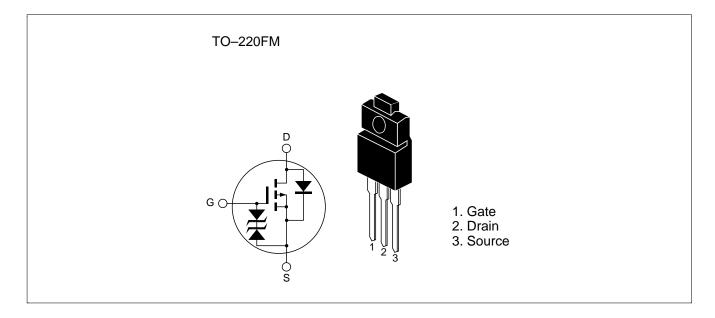
# HITACHI

ADE-208-658A (Z) 2nd. Edition Jun 1998

#### Features

- Low on-resistance  $R_{DS(on)} = 0.16 \Omega$  typ.
- 4 V gete drive devices
- High speed switching

### Outline





# **Absolute Maximum Ratings** (Ta = $25^{\circ}$ C)

Item	Symbol	Ratings	Unit	
Drain to source voltage	V <sub>DSS</sub>	-60	V	
Gate to source voltage	V <sub>GSS</sub>	±20	V	
Drain current	I <sub>D</sub>	-10	A	
Drain peak current	Note1 D(pulse)	-40	A	
Body-drain diode reverse drain current	I <sub>DR</sub>	-10	A	
Avalenche current	AP Note3	-10	А	
Avalenche energy	E <sub>AR</sub> <sup>Note3</sup>	8.5	mJ	
Channel dissipation	Pch <sup>Note2</sup>	20	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Note: 1.  $PW \le 10\mu s$ , duty cycle  $\le 1 \%$ 

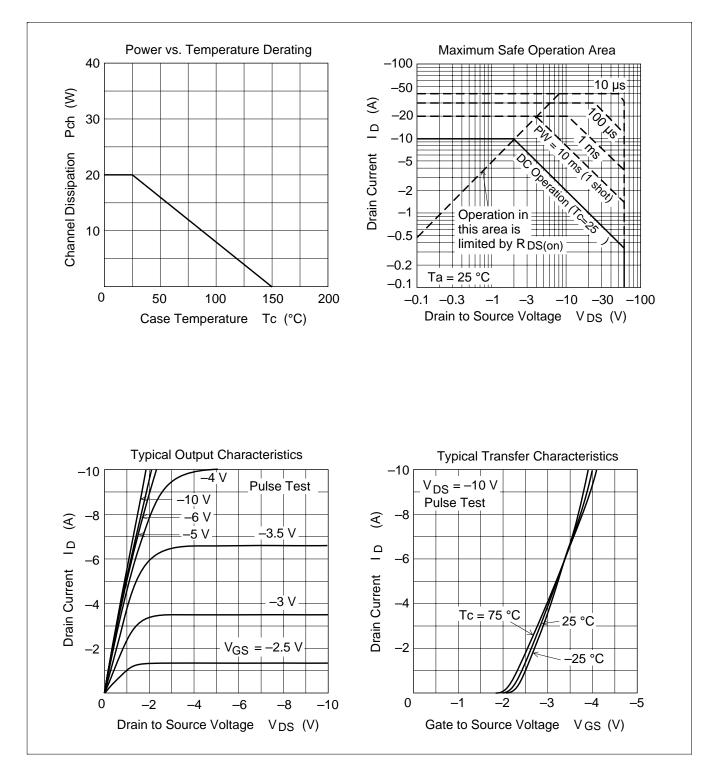
- 2. Value at  $Tc = 25^{\circ}C$
- 3. Value at Tch = 25°C, Rg  $\geq$  50  $\Omega$

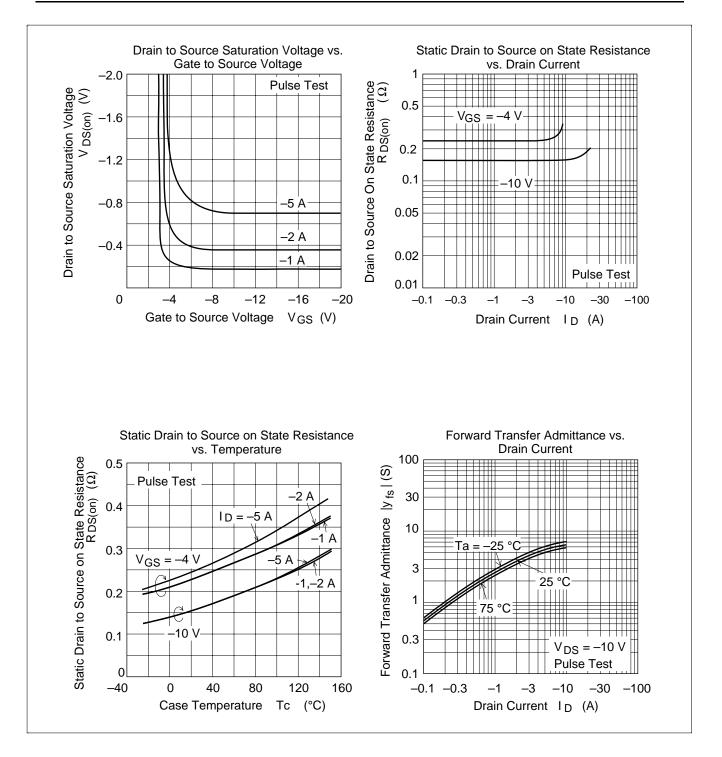
# **Electrical Characteristics** (Ta = 25°C)

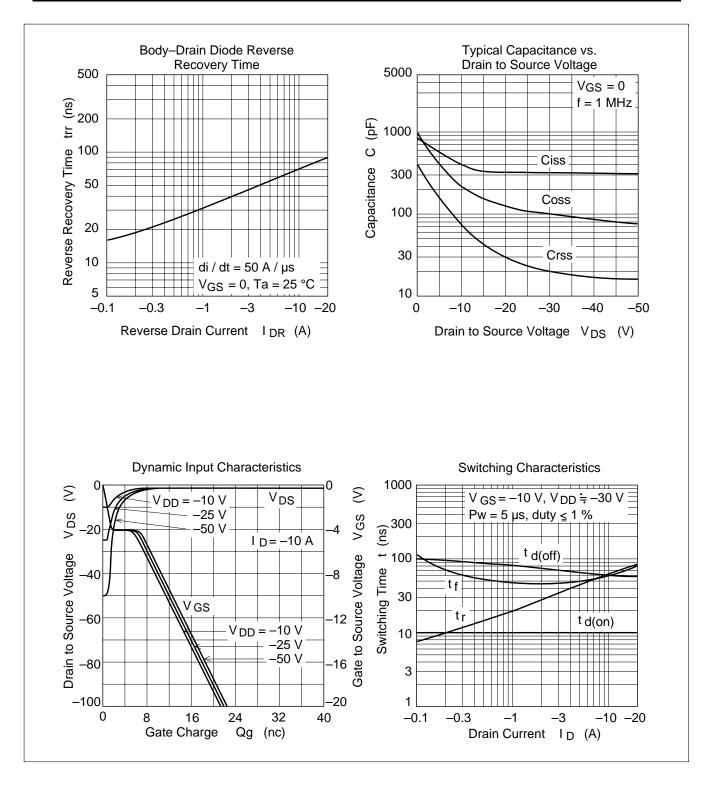
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V <sub>(BR)DSS</sub>	-60	_		V	$I_{\rm D} = -10 {\rm mA}, V_{\rm GS} = 0$
Gate to source breakdown voltage	V <sub>(BR)GSS</sub>	±20			V	$I_{g} = \pm 100 \mu A, V_{DS} = 0$
Zero gate voltege drain current	I <sub>DSS</sub>		_	-10	μA	$V_{\rm DS} = -60  \text{V},  V_{\rm GS} = 0$
Gate to source leak current	I <sub>GSS</sub>		_	±10	μΑ	$V_{GS} = \pm 16V, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-1.0	_	-2.0	V	$I_{\rm D} = -1$ mA, $V_{\rm DS} = -10$ V
Static drain to source on state	R <sub>DS(on)</sub>		0.16	0.21	Ω	$I_{\rm D} = -5A, V_{\rm GS} = -10V^{\rm Note4}$
resistance	R <sub>DS(on)</sub>		0.23	0.36	Ω	$I_{\rm D} = -5A, V_{\rm GS} = -4V^{\rm Note4}$
Forward transfer admittance	y <sub>fs</sub>	3.5	5.5	_	S	$I_{\rm D} = -5A, V_{\rm DS} = -10V^{\rm Note4}$
Input capacitance	Ciss		400		pF	$V_{DS} = -10V$
Output capacitance	Coss		220		pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss		75	_	pF	f = 1MHz
Turn-on delay time	t <sub>d(on)</sub>		10	_	ns	$V_{GS} = -10V, I_{D} = -5A$
Rise time	t <sub>r</sub>		45	_	ns	$R_{L} = 6\Omega$
Turn-off delay time	t <sub>d(off)</sub>		65		ns	_
Fall time	t <sub>f</sub>		50		ns	_
Body-drain diode forward voltage	V <sub>DF</sub>		-1.2	_	V	$I_{\rm F} = -10$ A, $V_{\rm GS} = 0$
Body–drain diode reverse recovery time	t <sub>rr</sub>		70		ns	$I_{F} = -10A, V_{GS} = 0$ diF/ dt = 50A/µs

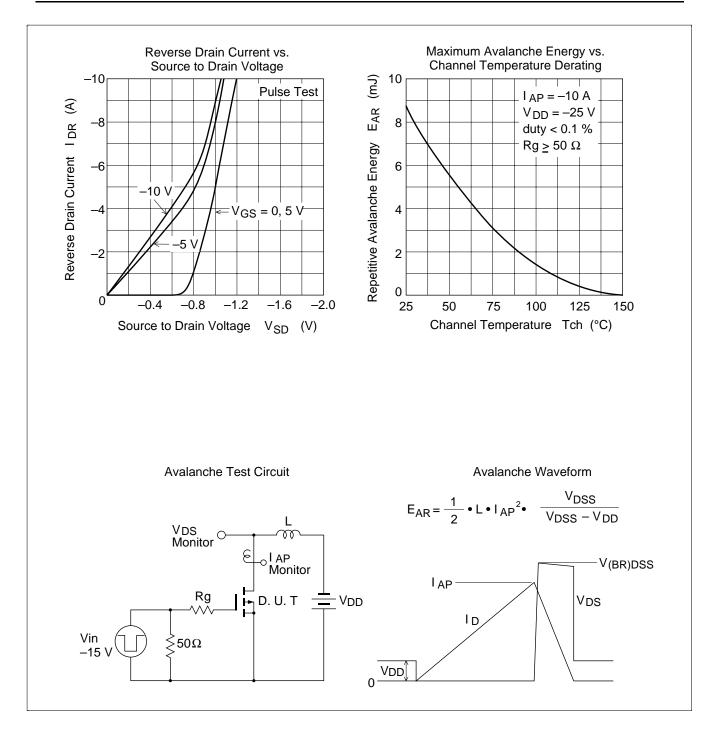
Note: 4. Pulse test

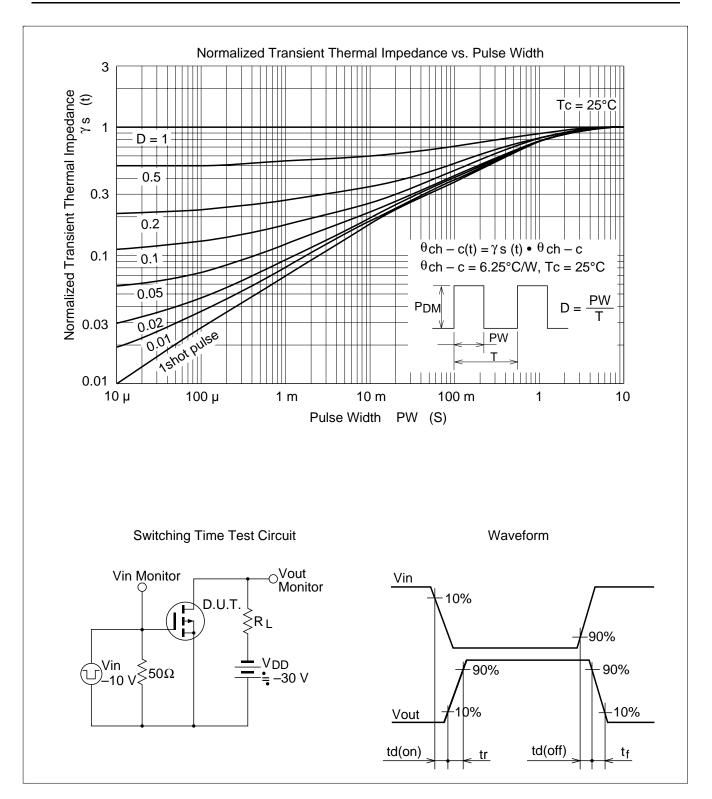
# **Main Characteristics**





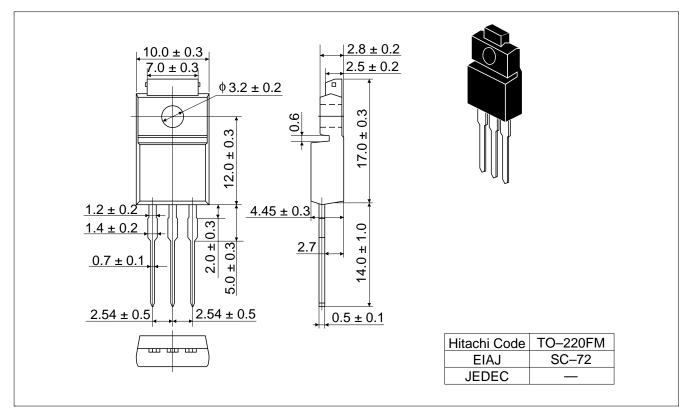






# **Package Dimensions**

Unit: mm



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